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Ultralow V_F Ultrafast Rectifier, 6 A FRED Pt[®]



LINKS TO ADDITIONAL RESOURCES



PRIMARY CHARACTERISTICS									
I _{F(AV)}	6 A								
V _R	600 V								
V _F at I _F	0.87 V								
t _{rr} (typ.)	59 ns								
T _J max.	175 °C								
Package	DPAK (TO-252AA)								
Circuit configuration	Single								

FEATURES

- Ultrafast recovery time, extremely low V_F and soft recovery
- 175 °C maximum operating junction temperature
- For PFC DCM operation
- Low leakage current
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

DESCRIPTION / APPLICATIONS

State of the art hyperfast recovery rectifiers designed with optimized performance of forward voltage drop, hyperfast recovery time, and soft recovery.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in PFC boost stage in the AC/DC section of SMPS inverters or as freewheeling diodes. Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

MECHANICAL DATA

Case: DPAK (TO-252AA)

Molding compound meets UL 94 V-0 flammability rating

Terminals: matte tin plated leads, solderable per J-STD-002

ABSOLUTE MAXIMUM RATINGS										
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS						
Peak repetitive reverse voltage	V _{RRM}		600	V						
Average rectified forward current	I _{F(AV)}	T _C = 156 °C	6							
Non-repetitive peak surge current	I _{FSM}	$T_J = 25 \ ^{\circ}C$	80	А						
Peak repetitive forward current	I _{FM}	$T_{C} = 156 \text{ °C}, f = 20 \text{ kHz}, d = 50 \text{ \%}$	12							
Operating junction and storage temperatures	TJ, T _{Stg}		-65 to +175	°C						

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)										
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS				
Breakdown voltage, blocking voltage	V _{BR} , V _R	I _R = 100 μA	600	-	-	v				
Forward voltage	V _F	I _F = 6 A	-	0.99	1.25	v				
		I _F = 6 A, T _J = 150 °C	-	0.87	1.05					
		$V_{R} = V_{R}$ rated	-	-	5					
Reverse leakage current	I _R	$T_J = 150 \text{ °C}, V_R = V_R \text{ rated}$	-	-	125	μA				
Junction capacitance	CT	V _R = 600 V	-	3.5	-	pF				
Series inductance	L _S	Measured lead to lead 5 mm from package body	-	8	-	nH				

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COMPLIANT



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DYNAMIC RECOVERY CHARACTERISTICS ($T_J = 25$ °C unless otherwise specified)										
PARAMETER	SYMBOL	TEST CO	NDITIONS	MIN.	TYP.	MAX.	UNITS			
Reverse recovery time		$I_F = 1 \text{ A}, dI_F/dt = 10$	0 A/µs, V _R = 30 V	-	59	70				
	+	$I_F = 1 \text{ A}, dI_F/dt = 50$	-	75	-	ns				
	t _{rr}	T _J = 25 °C		-	154	-	115			
		T _J = 125 °C	I _F = 6 A dI _F /dt = 200 A/μs V _R = 390 V	-	215	-				
Peak recovery current	I _{RRM}	T _J = 25 °C		-	13.3	-	А			
Peak recovery current		T _J = 125 °C		-	15.4	-				
Reverse recovery charge	0	T _J = 25 °C		-	1055	-	nC			
	Q _{rr}	T _J = 125 °C		-	1600	-	lic			

THERMAL - MECHANICAL SPECIFICATIONS										
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS				
Maximum junction and storage temperature range	T _J , T _{Stg}		-65	-	175	°C				
Thermal resistance, junction to case	R _{thJC}		-	-	3	°C/W				
Approximate weight				0.3		g				
Marking device		Case style DPAK (TO-252AA)	6EWL06FN							

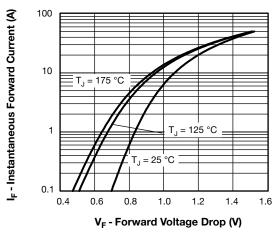


Fig. 1 - Typical Forward Voltage Drop Characteristics

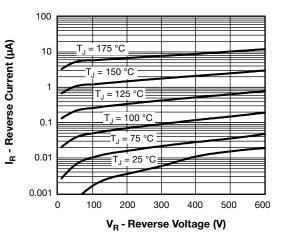
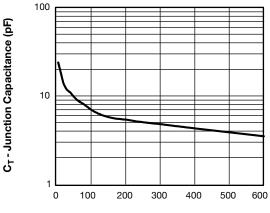


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage



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V_R - Reverse Voltage (V)

Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

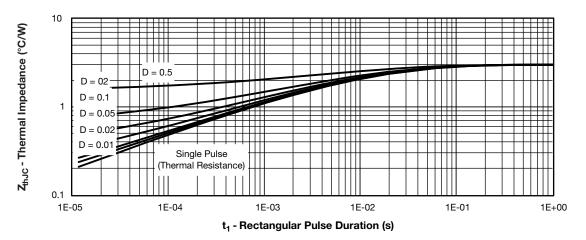


Fig. 4 - Maximum Thermal Impedance ZthJC Characteristics

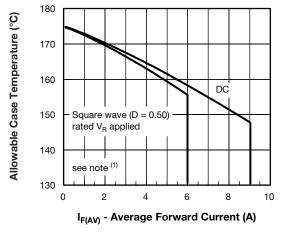


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

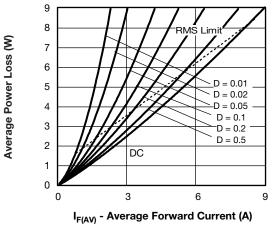


Fig. 6 - Forward Power Loss Characteristics

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350 300 250 t_{rr} (nC) 200 6 A, T_J = 125 °C 150 100 6 A, T_J = 25 °C 50 100 1000 dl_Fdt (A/µs)

Fig. 7 - Typical Reverse Recovery Time vs. dl_F/dt

Note

- ⁽¹⁾ Formula used: $T_C = T_J (Pd + Pd_{REV}) \times R_{thJC}$;
- $\begin{array}{l} \mathsf{Pd} = \mathsf{forward} \ \mathsf{power} \ \mathsf{loss} = \mathsf{I}_{\mathsf{F}(\mathsf{AV})} \times \mathsf{V}_{\mathsf{FM}} \ \mathsf{at} \ (\mathsf{I}_{\mathsf{F}(\mathsf{AV})}/\mathsf{D}) \ (\mathsf{see} \ \mathsf{fig.} \ \mathsf{6}); \\ \mathsf{Pd}_{\mathsf{REV}} = \mathsf{inverse} \ \mathsf{power} \ \mathsf{loss} = \mathsf{V}_{\mathsf{R1}} \times \mathsf{I}_{\mathsf{R}} \ (\mathsf{1} \mathsf{D}); \ \mathsf{I}_{\mathsf{R}} \ \mathsf{at} \ \mathsf{V}_{\mathsf{R1}} = \mathsf{rated} \ \mathsf{V}_{\mathsf{R}} \end{array}$

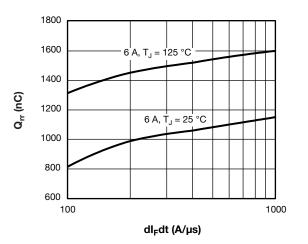


Fig. 8 - Typical Stored Charge vs. dl_F/dt

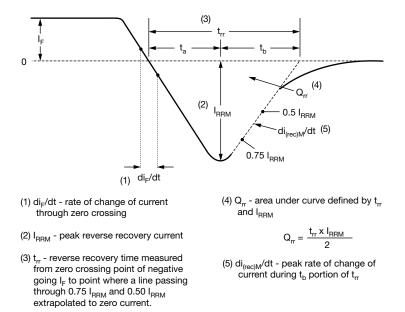


Fig. 9 - Reverse Recovery Waveform and Definitions

VS-6EWL06FN-M3

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ORDERING INFORMATION TABLE

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Device code	VS-	6	Е	w	L	06	FN	TRL	-M3
		2	(3)	(4)	(5)	(6)	(7)		(9)
	1	- Visl	nav Sen	niconduc	0	0	0	Ú	0
			-	ng (6 = 0	-				
	3			iguratior					
	<u> </u>		single c	-					
	4		-						
		W = D-PAK							
	5	- L=	low V _F ,	fast rec	overy				
	6	- Vol	tage rati	ng (06 =	= 600 V))			
	7	- FN	= TO-25	52AA					
	8	- • N	one = tu	lbe					
		• TI	R = tape	and ree	el				
		• TI	RL = tap	e and re	eel (left	orienteo	4)		
	_	• TI	RR = tap	be and r	eel (rigł	nt orient	ed)		
	9	- Env	rironmer	ntal digit	:				
		-M3	s = halog	gen-free	, RoHS	complia	ant and	termina	tions le

ORDERING INFORMATION (Example)									
PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION							
VS-6EWL06FN-M3	75	Antistatic plastic tube							
VS-6EWL06FNTR-M3	2000	13" diameter reel							
VS-6EWL06FNTRL-M3	3000	13" diameter reel							
VS-6EWL06FNTRR-M3	3000	13" diameter reel							

LINKS TO RELATED DOCUMENTS								
Dimensions	www.vishay.com/doc?95627							
Part marking information	www.vishay.com/doc?95176							
SPICE model	www.vishay.com/doc?95218							





D-PAK (TO-252AA) "M"

DIMENSIONS in millimeters and inches



SYMBOL	MILLIN	IETERS	INC	HES	NOTES	NOTES		MILLIN	IETERS	INC	HES	NOTES
STNIDUL	MIN.	MAX.	MIN.	MAX.	NOTES		SYMBOL	MIN.	MAX.	MIN.	MAX.	NOTES
А	2.18	2.39	0.086	0.094			е	2.29	BSC	0.090	BSC	
A1	-	0.13	-	0.005			Н	9.40	10.41	0.370	0.410	
b	0.64	0.89	0.025	0.035			L	1.40	1.78	0.055	0.070	
b2	0.76	1.14	0.030	0.045			L1	2.74	BSC	0.108	REF.	
b3	4.95	5.46	0.195	0.215	3		L2	0.51 BSC		0.020 BSC		
С	0.46	0.61	0.018	0.024			L3	0.89	1.27	0.035	0.050	3
c2	0.46	0.89	0.018	0.035			L4	-	1.02	-	0.040	
D	5.97	6.22	0.235	0.245	5		L5	1.14	1.52	0.045	0.060	2
D1	5.21	-	0.205	-	3		Ø	0°	10°	0°	10°	
E	6.35	6.73	0.250	0.265	5		Ø1	0°	15°	0°	15°	
E1	4.32	-	0.170	-	3		Ø2	25°	35°	25°	35°	

Notes

⁽¹⁾ Dimensioning and tolerancing as per ASME Y14.5M-1994

⁽²⁾ Lead dimension uncontrolled in L5

⁽³⁾ Dimension D1, E1, L3 and b3 establish a minimum mounting surface for thermal pad

(4) Section C - C dimension apply to the flat section of the lead between 0.13 and 0.25 mm (0.005 and 0.10") from the lead tip

(5) Dimension D, and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body

⁽⁶⁾ Dimension b1 and c1 applied to base metal only

⁽⁷⁾ Datum A and B to be determined at datum plane H

⁽⁸⁾ Outline conforms to JEDEC[®] outline TO-252AA



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